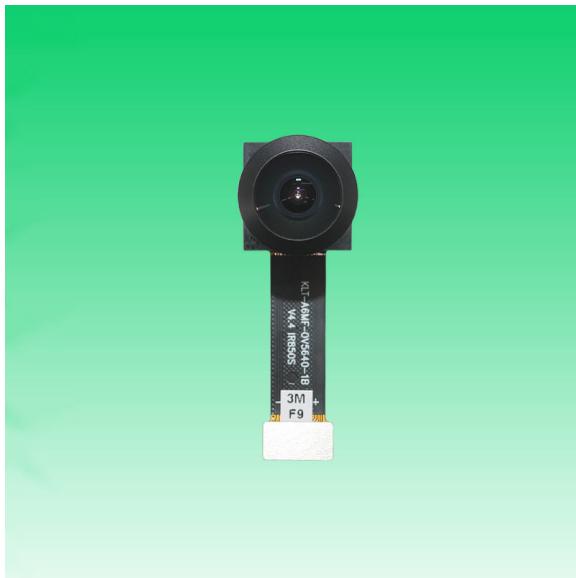


**KLT-A6MF-OV5640-1B V4.4 IR850S****5MP OmniVision OV5640-1B MIPI Interface M12 850nm IR Pass  
Fixed Focus Camera Module**

Front View



Back View

**Specifications**

Camera Module No.	<b>KLT-A6MF-OV5640-1B V4.4 IR850S</b>
Resolution	5MP
Image Sensor	OV5640-1B
Sensor Type	1/4"
Pixel Size	1.4 um x 1.4 um
EFL	1.76 mm
F.NO	2.70
Pixel	2592 x 1944
View Angle	162.0°(DFOV) 124.0°(HFOV) 91.0°(VFOV)
Lens Dimensions	13.60 x 13.60 x 17.10 mm
Module Size	40.00 x 13.60 mm
Module Type	Fixed Focus
Interface	MIPI
Auto Focus VCM Driver IC	Embedded
Lens Type	850nm IR Pass
Operating Temperature	-30°C to +70°C
Mating Connector	AXT524124

**KLT-A6MF-OV5640-1B V4.4 IR850S**

**5MP OmniVision OV5640-1B MIPI Interface M12 850nm IR Pass  
Fixed Focus Camera Module**



Top View



Side View



Bottom View



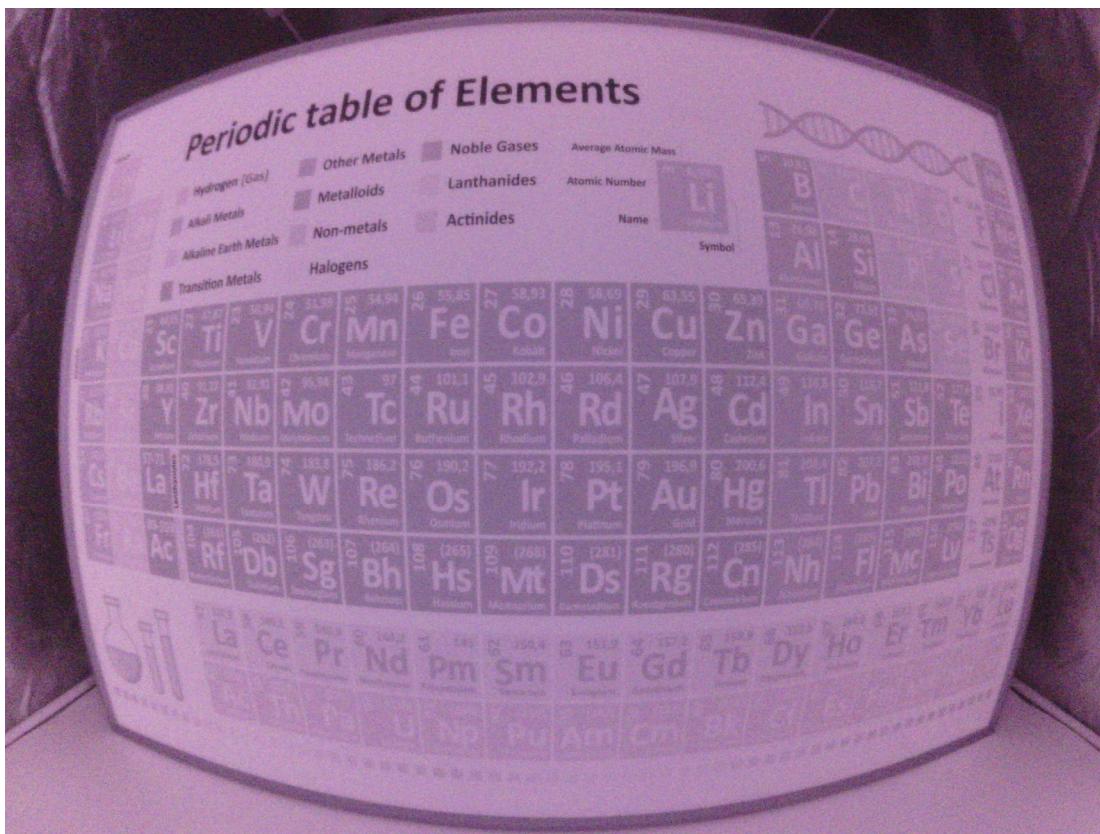
Mating Connector

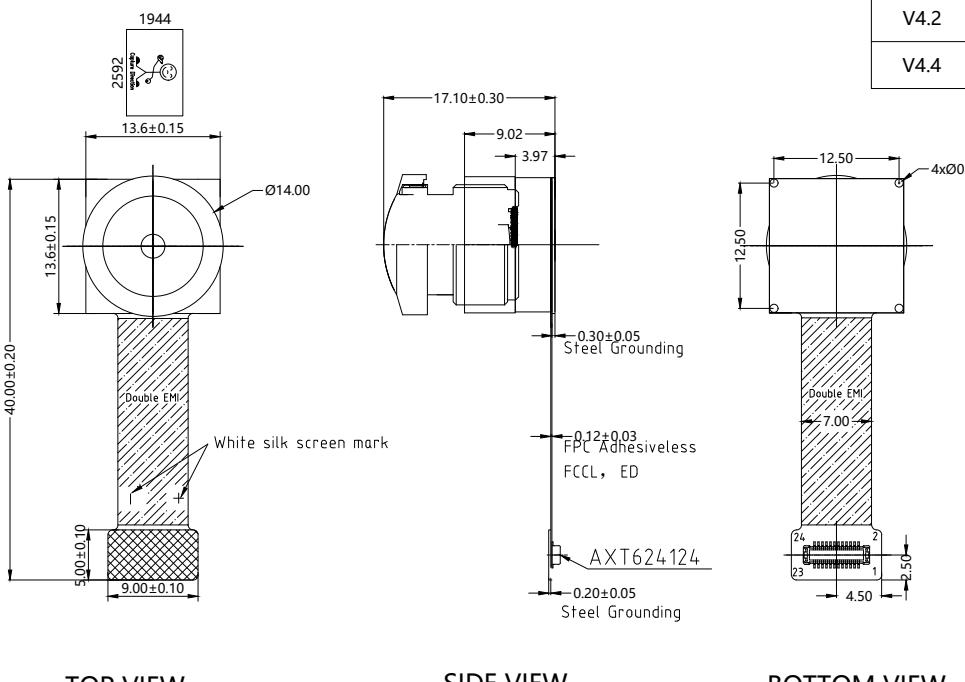


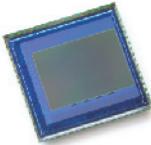
[www.KaiLapTech.com](http://www.KaiLapTech.com) [sales@KaiLapTech.com](mailto:sales@KaiLapTech.com) Tel: (852) 6908 1256 Fax: (852) 3017 6778



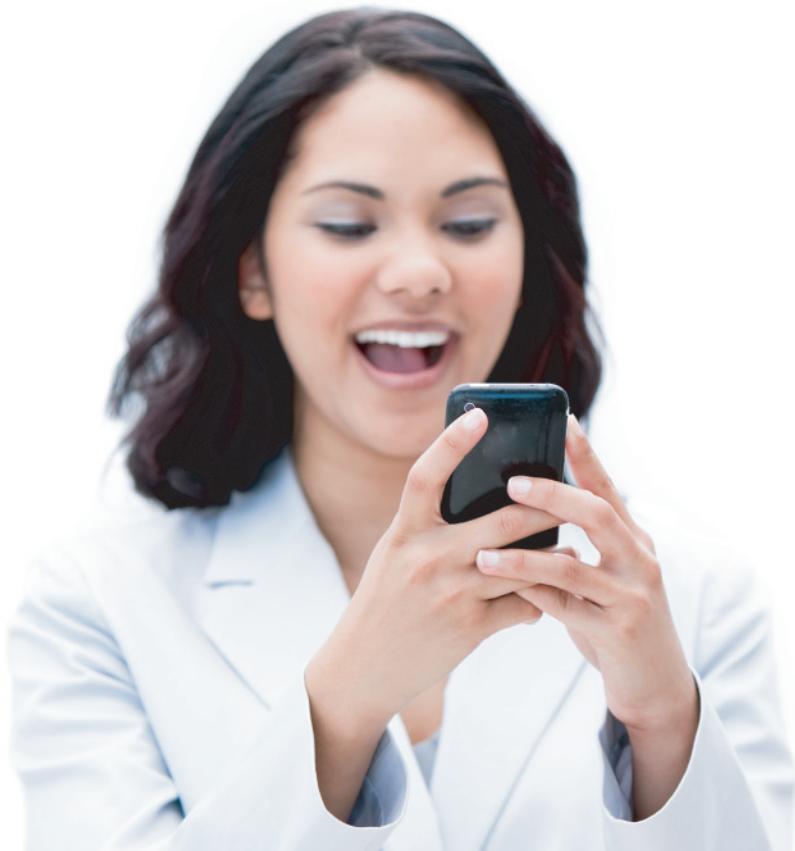
[www.KaiLapTech.com](http://www.KaiLapTech.com) [sales@KaiLapTech.com](mailto:sales@KaiLapTech.com) Tel: (852) 6908 1256 Fax: (852) 3017 6778



A	B	C	D	E																		
<b>RoHS</b>				<table border="1"> <thead> <tr> <th>Version</th><th>Information</th></tr> </thead> <tbody> <tr> <td>V1.0</td><td>First Version</td></tr> <tr> <td>V2.0</td><td>Change lens and holder</td></tr> <tr> <td>V4.0</td><td>Change FPC length</td></tr> <tr> <td>V4.2</td><td>Add double EMI</td></tr> <tr> <td>V4.4</td><td>Change capture direction</td></tr> </tbody> </table>	Version	Information	V1.0	First Version	V2.0	Change lens and holder	V4.0	Change FPC length	V4.2	Add double EMI	V4.4	Change capture direction						
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1 NC 2 AVDD 2.8V 3 SCL 4 SDA 5 RESET 6 PWDN 7 DOVDD 1.8V 8 DVDD 1.5V 9 GND 10 XCLK 11 DGND 12 DGND 13 MDN1 14 MCN 15 MDP1 16 MCP 17 DGND 18 DGND 19 DGND 20 MDN0 21 DGND 22 MDP0 23 DGND 24 DGND																						
																						
<b>Parameters:</b> 1. Sensor specification: Image Sensor: OV5640-1B Pixel: 1.4um*1.4um Lens Type: 1/4 Important Voltage Description: DVDD1.5V (external power supply);				<p><b>Kai Lap Technologies Group Ltd</b></p> <table border="1"> <tr> <td>Designed By</td> <td>Kevin</td> <td>Model Name:</td> <td colspan="3">KLT-A6MF-OV5640-1B V4.4 IR850S</td> </tr> <tr> <td>Checked By</td> <td>Jacky</td> <td>Projection Type:</td> <td>Unit:</td> <td>Date:</td> <td>8/16/2025</td> </tr> <tr> <td></td> <td></td> <td>Third Angle</td> <td>mm</td> <td>Sheet:</td> <td>1 of 1</td> </tr> </table>	Designed By	Kevin	Model Name:	KLT-A6MF-OV5640-1B V4.4 IR850S			Checked By	Jacky	Projection Type:	Unit:	Date:	8/16/2025			Third Angle	mm	Sheet:	1 of 1
Designed By	Kevin	Model Name:	KLT-A6MF-OV5640-1B V4.4 IR850S																			
Checked By	Jacky	Projection Type:	Unit:	Date:	8/16/2025																	
		Third Angle	mm	Sheet:	1 of 1																	
2. Lens specification: FOV: 162°(D);124°(H);91°(V) F/NO.: 2.7 TV distortion: <17% Focal length: 1.76mm Composition: 6G+ IR FILTER IR Cut Coating: 850nm±10nm@50%																						
A      B      C      D      E																						



# OV5640 5-megapixel product brief



## 1/4-inch, 5-Megapixel SOC Image Sensor Optimized for High-Volume Mobile Markets



available in  
a lead-free  
package

The OV5640 delivers a complete 5-megapixel camera solution on a single chip, aimed at offering cost efficiencies that serve the high-volume autofocus (AF) camera phone market. The system-on-a-chip (SOC) sensor features OmniVision's 1.4 micron OmniBSI™ backside illumination architecture to deliver excellent pixel performance and best-in-class low-light sensitivity, while enabling ultra compact camera module designs of 8.5 mm x 8.5 mm with <6 mm z-height. The OV5640 provides the full functionality of a complete camera, including anti-shake technology, AF control, and MIPI while being easier to tune than two-chip solutions, making it an ideal choice in terms of cost, time-to-market and ease of platform integration.

The OV5640 enables 720p HD video at 60 frames per second (fps) and 1080p HD video at 30 fps with complete user control over formatting and output data transfer. The 720p/60 HD video is captured in full field of view (FOV) with 2 x 2 binning, which doubles the sensitivity and improves the signal-to-noise ratio (SNR). Additionally, a unique post-binning re-sampling filter function removes zigzag artifacts around slant edges and minimizes spatial artifacts to deliver even sharper, crisper

color images. To further improve camera performance and user experience, the OV5640 features an internal anti-shake engine for image stabilization, and it supports Scalado™ tagging for faster image preview and zoom.

The OV5640 offers a digital video port (DVP) parallel interface and a high-speed dual lane MIPI interface, supporting multiple output formats. An integrated JPEG compression engine simplifies data transfer for bandwidth-limited interfaces. The sensor's automatic image control functions include automatic exposure control (AEC), automatic white balance (AWB), automatic band filter (ABF), 50/60 Hz automatic luminance detection, and automatic black level calibration (ABLC). The OV5640 delivers programmable controls for frame rate, AEC/AGC 16-zone size/position/weight control, mirror and flip, cropping, windowing, and panning. It also offers color saturation, hue, gamma, sharpness (edge enhancement), lens correction, defective pixel canceling, and noise canceling to improve image quality.

Find out more at [www.ovt.com](http://www.ovt.com).

**Omni***Vision*

## applications

- cellular phones
- toys
- PC multimedia
- digital still cameras

## ordering information

- **OV05640-A71A-1B** (color, lead-free)  
71-pin CSP

## features

- 1.4  $\mu\text{m} \times 1.4 \mu\text{m}$  pixel with OmniBSI technology for high performance (high sensitivity, low crosstalk, low noise, improved quantum efficiency)
- optical size of 1/4"
- automatic image control functions: automatic exposure control (AEC), automatic white balance (AWB), automatic band filter (ABF), automatic 50/60 Hz luminance detection, and automatic black level calibration (ABLC)
- programmable controls for frame rate, AEC/AGC 16-zone size/position/weight control, mirror and flip, cropping, windowing, and panning
- image quality controls: color saturation, hue, gamma, sharpness (edge enhancement), lens correction, defective pixel canceling, and noise canceling
- support for output formats: RAW RGB, RGB565/555/444, CCIR656, YUV422/420, YCbCr422, and compression
- support for video or snapshot operations
- support for internal and external frame synchronization for frame exposure mode
- support for LED and flash strobe mode
- support for horizontal and vertical sub-sampling, binning
- support for minimizing artifacts on binned image
- support for data compression output
- support for anti-shake
- standard serial SCCB interface
- digital video port (DVP) parallel output interface and dual lane MIPI output interface
- embedded 1.5V regulator for core power
- programmable I/O drive capability, I/O tri-state configurability
- support for black sun cancellation
- support for images sizes: 5 megapixel, and any arbitrary size scaling down from 5 megapixel
- support for auto focus control (AFC) with embedded AF VCM driver
- embedded microcontroller
- suitable for module size of 8.5 x 8.5 x <6mm with both CSP and RW packaging

## key specifications (typical)

- **active array size:** 2592 x 1944
- **power supply:**
  - core: 1.425 ~ 1.675V (with embedded 1.5V regulator)
  - analog: 2.6 ~ 3.0V (2.8V typical)
  - I/O: 1.8V / 2.8V
- **power requirements:**
  - active: 140 mA
  - standby: 20  $\mu\text{A}$
- **temperature range:**
  - operating: -30°C to 70°C junction temperature (see [table 8-2](#))
  - stable image: 0°C to 50°C junction temperature (see [table 8-2](#))
- **output formats:** 8-/10-bit RGB RAW output
- **lens size:** 1/4"
- **lens chief ray angle:** 24° (see [figure 10-2](#))
- **input clock frequency:** 6~27 MHz
- **max S/N ratio:** 36 dB
- **dynamic range:** 68 dB @ 8x gain
- **maximum image transfer rate:**
  - QSXGA (2592x1944): 15 fps
  - 1080p: 30 fps
  - 1280x960: 45 fps
  - 720p: 60 fps
  - VGA (640x480): 90 fps
- **sensitivity:** 600 mV/Lux-sec
- **shutter:** rolling shutter / frame exposure
- **maximum exposure interval:** 1964 x  $t_{\text{ROW}}$
- **pixel size:** 1.4  $\mu\text{m} \times 1.4 \mu\text{m}$
- **dark current:** 8 mV/s @ 60°C junction temperature
- **image area:** 3673.6  $\mu\text{m} \times 2738.4 \mu\text{m}$
- **package dimensions:** 5985  $\mu\text{m} \times 5835 \mu\text{m}$



Socket

Header

## Compliance with RoHS Directive

### NARROW-PITCH, THIN AND SLIM CONNECTOR FOR BOARD-TO-FPC CONNECTION

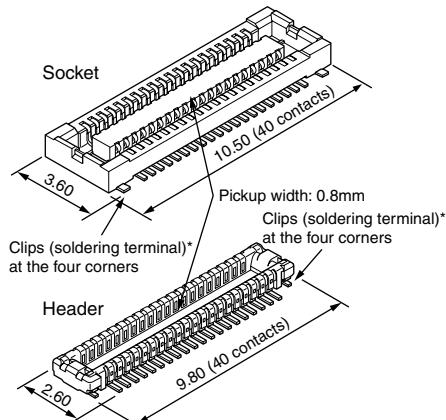
### NARROW PITCH (0.4 mm) CONNECTORS F4S SERIES

## FEATURES

### 1. Space-saving (3.6 mm widthwise)

The required space is smaller than our F4 series (40-contact type):  
Socket — 27% smaller,  
Header — 38% smaller

The small size contributes to the miniaturization of target equipment.



\* Clips for preventing the solder joints from being removed

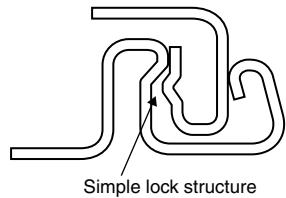
### 2. Highly reliable

**TOUGH CONTACT** has strong resistance to adverse environments.

(See Page 6 for details of the structure)

Note: If extra resistance to shock caused by dropping is required, we recommend using our previous F4 Series.

3. The simple lock structure gives tactile feedback that ensures a superior mating/unmating operation feel.



### 4. Gull-wing type terminals

The gull-wing type terminals facilitate automatic mounting inspections.

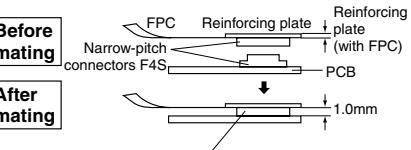
### 5. Connectors for inspection available

Connectors for inspection are available that are ideal for modular unit inspection and inspection in device assembly processes.

## APPLICATIONS

Compact portable devices “Cellular phones, DVC, Digital cameras, etc”

### Example of Board-to-FPC connections



The simple lock mechanism ensures that the connector clicks into position when it is inserted for reliable single-action insertion on the PCB.

## ORDERING INFORMATION

AXT      4

5: Narrow Pitch Connector F4S (0.4 mm pitch) Socket  
6: Narrow Pitch Connector F4S (0.4 mm pitch) Header

Number of contacts (2 digits)

Mated height

<Socket>

1: For mated height 1.0 mm  
2: For mated height 1.2 mm

<Header>

1: For mated height 1.0 mm  
2: For mated height 1.2 mm

Functions

<Socket, Header>

2: Without positioning bosses

Surface treatment (Contact portion / Terminal portion)

<Socket>

4: Base: Ni plating Surface: Au plating (for Ni barrier available)

<Header>

4: Base: Ni plating Surface: Au plating

Note: Please note that models with a mated height of 1.0 mm (7th digit of part number is “1”) and 1.2 mm (7th digit of part number is “2”) are not compatible.

# AXT5, 6

## PRODUCT TYPES TOUGH CONTACT

Mated height	Number of contacts	Part number		Packing	
		Socket	Header	Inner carton	Outer carton
1.0mm	10	AXT510124	AXT610124	3,000 pieces	6,000 pieces
	12	AXT512124	AXT612124		
	14	AXT514124	AXT614124		
	16	AXT516124	AXT616124		
	18	AXT518124	AXT618124		
	20	AXT520124	AXT620124		
	22	AXT522124	AXT622124		
	24	AXT524124	AXT624124		
	26	AXT526124	AXT626124		
	28	AXT528124	AXT628124		
	30	AXT530124	AXT630124		
	32	AXT532124	AXT632124		
	34	AXT534124	AXT634124		
	36	AXT536124	AXT636124		
	38	AXT538124	AXT638124		
	40	AXT540124	AXT640124		
	42	AXT542124	AXT642124		
	44	AXT544124	AXT644124		
	46	AXT546124	AXT646124		
	48	AXT548124	AXT648124		
	50	AXT550124	AXT650124		
	54	AXT554124	AXT654124		
	60	AXT560124	AXT660124		
	64	AXT564124	AXT664124		
	70	AXT570124	AXT670124		
	80	AXT580124	AXT680124		
1.2mm	10	AXT510224	AXT610224		
	30	AXT530224	AXT630224		
	40	AXT540224	AXT640224		
	50	AXT550224	AXT650224		
	80	AXT580224	AXT680224		

Notes: 1. Order unit: For mass production: in 1-inner-box (1-reel) units

Samples for mounting check: in 50-connector units. Please contact our sales office.

Samples: Small lot orders are possible. Please contact our sales office.

2. The above part numbers are for connectors without positioning bosses, which are standard. When ordering connectors with positioning bosses, please contact our sales office.

3. Please contact us for connectors having a number of contacts other than those listed above.

# SPECIFICATIONS

## 1. Characteristics

Item		Specifications	Conditions
Electrical characteristics	Rated current	0.3A/contact (Max. 5 A at total contacts)	
	Rated voltage	60V AC/DC	
	Breakdown voltage	150V AC for 1 min.	No short-circuiting or damage at a detection current of 1 mA when the specified voltage is applied for one minute.
	Insulation resistance	Min. 1,000MΩ (initial)	Using 250V DC megger (applied for 1 min.)
	Contact resistance	Max. 90mΩ	Based on the contact resistance measurement method specified by JIS C 5402.
Mechanical characteristics	Composite insertion force	Max. 0.981N/contacts × contacts (initial)	
	Composite removal force	Min. 0.165N/contacts × contacts	
	Contact holding force (Socket contact)	Min. 0.49N/contacts	Measuring the maximum force. As the contact is axially pull out.
Environmental characteristics	Ambient temperature	−55°C to +85°C	No freezing at low temperatures. No dew condensation.
	Soldering heat resistance	Peak temperature: 260°C or less (on the surface of the PC board around the connector terminals) 300°C within 5 sec. 350°C within 3 sec.	Infrared reflow soldering Soldering iron
	Storage temperature	−55°C to +85°C (product only) −40°C to +50°C (emboss packing)	No freezing at low temperatures. No dew condensation.
	Thermal shock resistance (header and socket mated)	5 cycles, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Sequence 1. −55.0°C, 30 minutes 2. ~, Max. 5 minutes 3. 85.0°C, 30 minutes 4. ~, Max. 5 minutes
	Humidity resistance (header and socket mated)	120 hours, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Bath temperature 40±2°C, humidity 90 to 95% R.H.
	Saltwater spray resistance (header and socket mated)	24 hours, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Bath temperature 35±2°C, saltwater concentration 5±1%
	H <sub>2</sub> S resistance (header and socket mated)	48 hours, contact resistance max. 90mΩ	Bath temperature 40±2°C, gas concentration 3±1 ppm, humidity 75 to 80% R.H.
Lifetime characteristics	Insertion and removal life	50 times	Repeated insertion and removal speed of max. 200 times/hours
Unit weight	20-contact type: Socket: 0.03 g Header: 0.01 g		

## 2. Material and surface treatment

Part name	Material	Surface treatment
Molded portion	LCP resin (UL94V-0)	—
Contact and Post	Copper alloy	Contact portion: Base: Ni plating Surface: Au plating Terminal portion: Base: Ni plating Surface: Au plating (except the terminal tips) The socket terminals close to the portion to be soldered have nickel barriers (exposed nickel portions). Metal clips: Sockets: Base: Ni plating Surface: Pd+Au flash plating (except the terminal tips) Headers: Base: Ni plating Surface: Au plating (except the terminal tips)

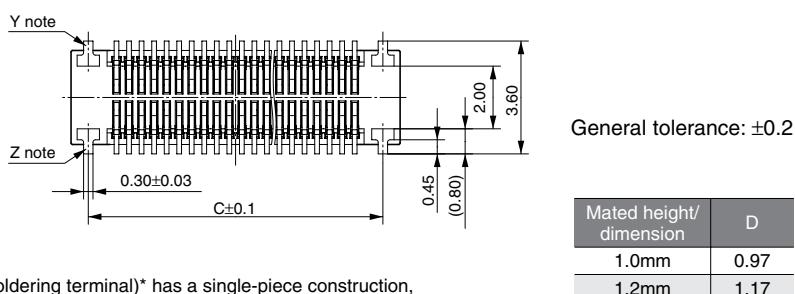
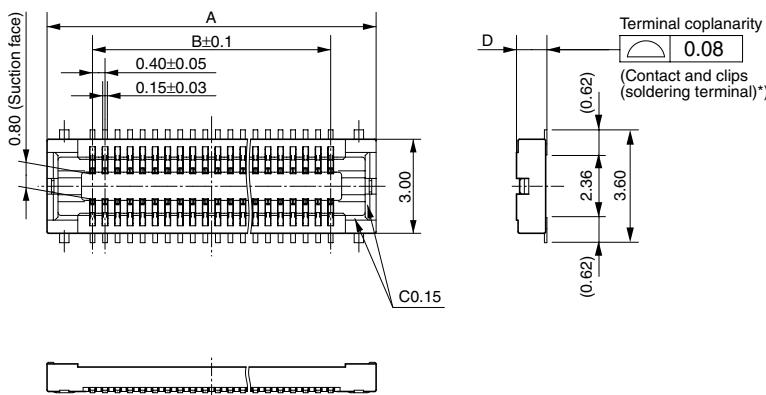
# AXT5, 6

## DIMENSIONS (Unit: mm)

The CAD data of the products with a **CAD Data** mark can be downloaded from: <http://panasonic-electric-works.net/ac>

Socket (Mated height: 1.0 mm and 1.2 mm)

### CAD Data



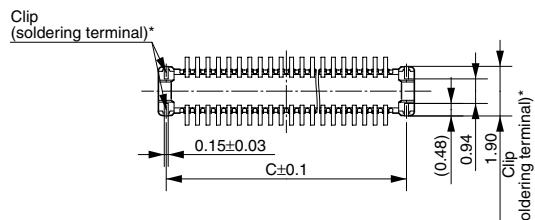
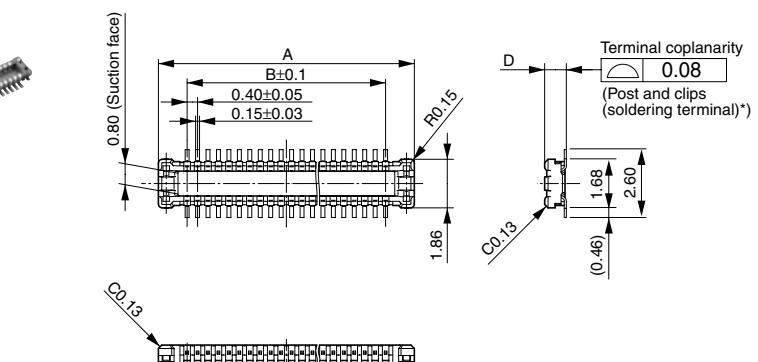
Note: Since the clip (soldering terminal)\* has a single-piece construction, sections Y and Z are electrically connected.

### Dimension table (mm)

Number of contacts/dimension	A	B	C
10	4.5	1.6	3.4
12	4.9	2.0	3.8
14	5.3	2.4	4.2
16	5.7	2.8	4.6
18	6.1	3.2	5.0
20	6.5	3.6	5.4
22	6.9	4.0	5.8
24	7.3	4.4	6.2
26	7.7	4.8	6.6
28	8.1	5.2	7.0
30	8.5	5.6	7.4
32	8.9	6.0	7.8
34	9.3	6.4	8.2
36	9.7	6.8	8.6
38	10.1	7.2	9.0
40	10.5	7.6	9.4
42	10.9	8.0	9.8
44	11.3	8.4	10.2
46	11.7	8.8	10.6
48	12.1	9.2	11.0
50	12.5	9.6	11.4
54	13.3	10.4	12.2
60	14.5	11.6	13.4
64	15.3	12.4	14.2
70	16.5	13.6	15.4
80	18.5	15.6	17.4

## Header (Mated height: 1.0 mm and 1.2 mm)

### CAD Data



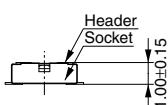
General tolerance: ±0.2

Mated height/dimension	D
1.0mm	0.97
1.2mm	1.17

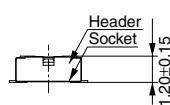
### Dimension table (mm)

Number of contacts/dimension	A	B	C
10	3.8	1.6	3.2
12	4.2	2.0	3.6
14	4.6	2.4	4.0
16	5.0	2.8	4.4
18	5.4	3.2	4.8
20	5.8	3.6	5.2
22	6.2	4.0	5.6
24	6.6	4.4	6.0
26	7.0	4.8	6.4
28	7.4	5.2	6.8
30	7.8	5.6	7.2
32	8.2	6.0	7.6
34	8.6	6.4	8.0
36	9.0	6.8	8.4
38	9.4	7.2	8.8
40	9.8	7.6	9.2
42	10.2	8.0	9.6
44	10.6	8.4	10.0
46	11.0	8.8	10.4
48	11.4	9.2	10.8
50	11.8	9.6	11.2
54	12.6	10.4	12.0
60	13.8	11.6	13.2
64	14.6	12.4	14.0
70	15.8	13.6	15.2
80	17.8	15.6	17.2

### • Socket and Header are mated



Mated height: 1.0 mm



Mated height: 1.2 mm

## Cameras Applications



Automotive Driver Pilot



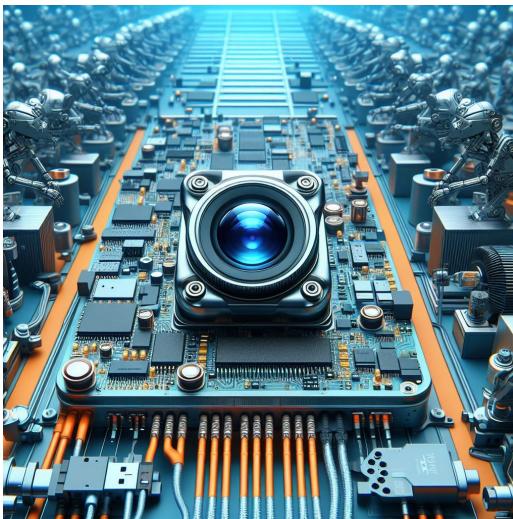
Live Streaming



Video Conference



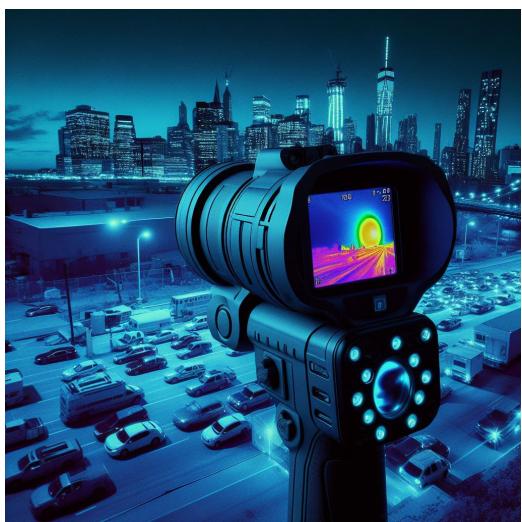
Eye Tracker Biometric Detection



Machine Vision



Agricultural Monitor



Night Vision Security



Drone and Sports Eagle Eyes



Interactive Pet Camera

## Cameras Applications



## Camera Module Pinout Definition Reference Chart

Pin Signal	Description
DGND GND	ground for digital circuit
AGND	ground for analog circuit
PCLK DCK	DVP PCLK output
XCLR PWDN XSHUTDOWN STANDBY	power down active high with internal pull-down resistor
MCLK XVCLK XCLK INCK	system input clock
RESET RST	reset active low with internal pull-up resistor
NC NULL	no connect
SDA SIO_D SIOD	SCCB data
SCL SIO_C SIOC	SCCB input clock
VSYNC XVS FSYNC	DVP VSYNC output
HREF XHS	DVP HREF output
DOVDD	power for I/O circuit
AFVDD	power for VCM circuit
AVDD	power for analog circuit
DVDD	power for digital circuit
STROBE FSTROBE	strobe output
FSIN	synchronize the VSYNC signal from the other sensor
SID	SCCB last bit ID input
ILPWM	mechanical shutter output indicator
FREX	frame exposure / mechanical shutter
GPIO	general purpose inputs
SLASEL	I2C slave address select
AFEN	CEN chip enable active high on VCM driver IC
<b>MIPI Interface</b>	
MDN0 DN0 MD0N DATA_N DMO1N	MIPI 1st data lane negative output
MDP0 DP0 MD0P DATA_P DMO1P	MIPI 1st data lane positive output
MDN1 DN1 MD1N DATA2_N DMO2N	MIPI 2nd data lane negative output
MDP1 DP1 MD1P DATA2_P DMO2P	MIPI 2nd data lane positive output
MDN2 DN2 MD2N DATA3_N DMO3N	MIPI 3rd data lane negative output
MDP2 DP2 MD2P DATA3_P DMO3P	MIPI 3rd data lane positive output
MDN3 DN3 MD3N DATA4_N DMO4N	MIPI 4th data lane negative output
MDP3 DP3 MD3P DATA4_P DMO4P	MIPI 4th data lane positive output
MCN CLKN CLK_N DCKN	MIPI clock negative output
MCP CLKP MCP CLK_P DCKN	MIPI clock positive output
<b>DVP Parallel Interface</b>	
D0 DO0 Y0	DVP data output port 0
D1 DO1 Y1	DVP data output port 1
D2 DO2 Y2	DVP data output port 2
D3 DO3 Y3	DVP data output port 3
D4 DO4 Y4	DVP data output port 4
D5 DO5 Y5	DVP data output port 5
D6 DO6 Y6	DVP data output port 6
D7 DO7 Y7	DVP data output port 7
D8 DO8 Y8	DVP data output port 8
D9 DO9 Y9	DVP data output port 9
D10 DO10 Y10	DVP data output port 10
D11 DO11 Y11	DVP data output port 11

## Camera Reliability Test

Reliability Inspection Item		Testing Method	Acceptance Criteria	
Category	Item			
Environmental	Storage Temperature	High 60°C 96 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 96 Hours	Temperature Chamber	No Abnormal Situation
	Operation Temperature	High 60°C 24 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 24 Hours	Temperature Chamber	No Abnormal Situation
	Humidity	60°C 80% 24 Hours	Temperature Chamber	No Abnormal Situation
	Thermal Shock	High 60°C 0.5 Hours Low -20°C 0.5 Hours Cycling in 24 Hours	Temperature Chamber	No Abnormal Situation
Physical	Drop Test (Free Falling)	Without Package 60cm	10 Times on Wood Floor	Electrically Functional
		With Package 60cm	10 Times on Wood Floor	Electrically Functional
	Vibration Test	50Hz X-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Y-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Z-Axis 2mm 30min	Vibration Table	Electrically Functional
	Cable Tensile Strength Test	Loading Weight 4 kg 60 Seconds Cycling in 24 Hours	Tensile Testing Machine	Electrically Functional
Electrical	ESD Test	Contact Discharge 2 KV	ESD Testing Machine	Electrically Functional
		Air Discharge 4 KV	ESD Testing Machine	Electrically Functional
	Aging Test	On/Off 30 Seconds Cycling in 24 Hours	Power Switch	Electrically Functional
	USB Connector	On/Off 250 Times	Plug and Unplug	Electrically Functional



Inspection Item		Inspection Method	Standard of Inspection
Category	Item		
Appearance	FPC/ PCB	Color	The Naked Eye
		Be Torn/Chopped	The Naked Eye
		Marking	The Naked Eye
	Holder	Scratches	The Naked Eye
		Gap	The Naked Eye
		Screw	The Naked Eye
		Damage	The Naked Eye
	Lens	Scratch	The Naked Eye
		Contamination	The Naked Eye
		Oil Film	The Naked Eye
		Cover Tape	The Naked Eye
Function	Image	No Communication	Test Board
		Bright Pixel	Black Board
		Dark Pixel	White board
		Blurry	The Naked Eye
		No Image	The Naked Eye
		Vertical Line	The Naked Eye
		Horizontal Line	The Naked Eye
		Light Leakage	The Naked Eye
		Blinking Image	The Naked Eye
		Bruise	Inspection Jig
		Resolution	Chart
		Color	The Naked Eye
		Noise	The Naked Eye
		Corner Dark	Less Than 100px By 100px
Dimension	Dimension	Color Resolution	The Naked Eye
		Height	The Naked Eye
		Width	The Naked Eye
		Length	The Naked Eye
		Overall	The Naked Eye

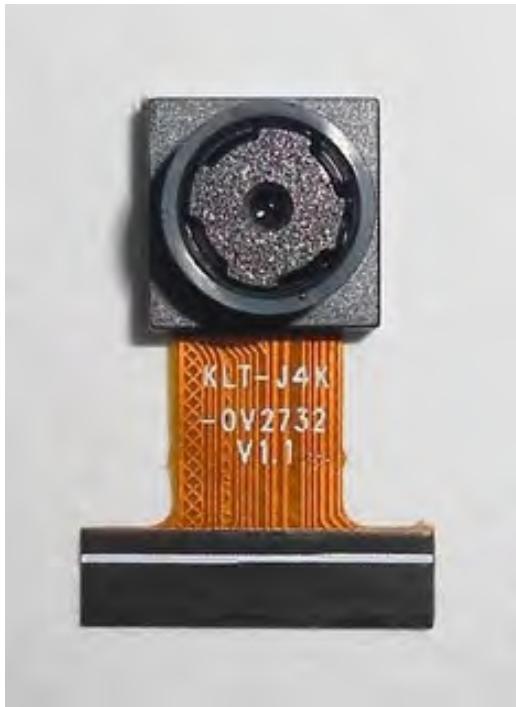


# CMOS CAMERA MODULES

your *BEST* camera module partner

## KLT Package Solutions

KLT Camera Module



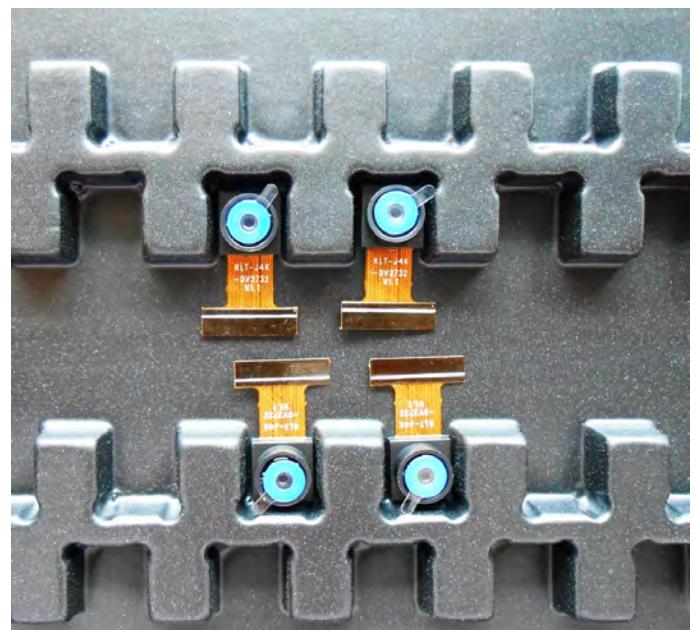
Complete with Lens Protection Film



Tray with Grid and Space



Place Cameras on the Tray



**Camera Modules Package Solution**

Full Tray of Cameras



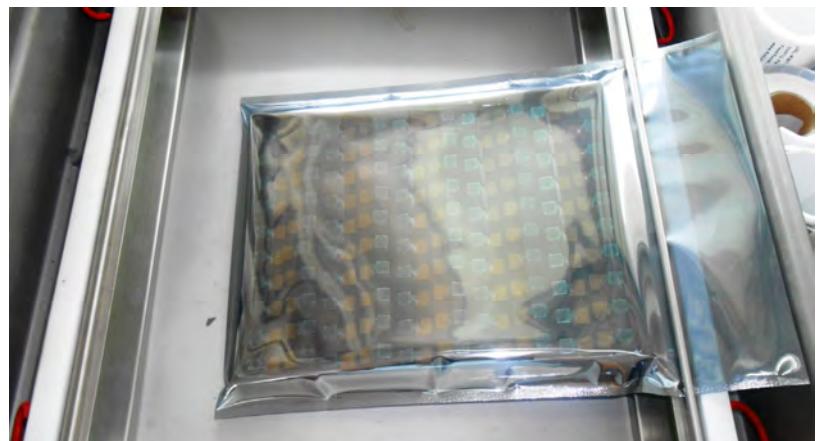
Cover Tray with Lid



Put Tray into Anti-Static Bag



Vacuum the Anti-Static Bag





# CMOS CAMERA MODULES

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## Camera Modules Package Solution

### Sealed Vacuum Bag with Labels

1. Model and Description 2. Quantity 3. Shipping Date 4. Caution



[www.KaiLapTech.com](http://www.KaiLapTech.com) [sales@KaiLapTech.com](mailto:sales@KaiLapTech.com) Tel: (852) 6908 1256 Fax: (852) 3017 6778

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**Large Order Package Solution**

Place Foam Sheets Between Trays



Foam Sheets are Slightly Larger than Trays



Place Foam Sheets and Trays into Box



Foam Sheets are Tightly Fitting Box





# CMOS CAMERA MODULES

*your BEST camera module partner*

## Small Order Package Solution

Place Foam Sheets and Trays into Small Box



Foam Sheets are Nicely Fitting the Small Box



Package in Small Box for Shipment

Place Small Boxes into Larger Box



[www.KaiLapTech.com](http://www.KaiLapTech.com) [sales@KaiLapTech.com](mailto:sales@KaiLapTech.com) Tel: (852) 6908 1256 Fax: (852) 3017 6778

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## Carbon Box Package Solution

Seal the Carbon Box

Final Package Labelled Box



### Carbon Box Ready for Shipment

1. Delivery Address and Phone No. 2. Box No. and Ship Date 3. Fragile Caution



[www.KaiLapTech.com](http://www.KaiLapTech.com) [sales@KaiLapTech.com](mailto:sales@KaiLapTech.com) Tel: (852) 6908 1256 Fax: (852) 3017 6778

## Sample Order Package Solution

Place Sample into Small Anti-Static Bag



Place Connectors into Small Ant-Static Bag



### Sample Labels on the Small Bag

1. Camera Module or Connector Model 2. Shipping Date and Quantity 3. Caution





## Connectors Large Order Package Solution

Connectors in a Wheel



Label Connectors in the Wheel



The Wheel is Perfectly Fitting the Box



Connectors Box Ready for Shipment

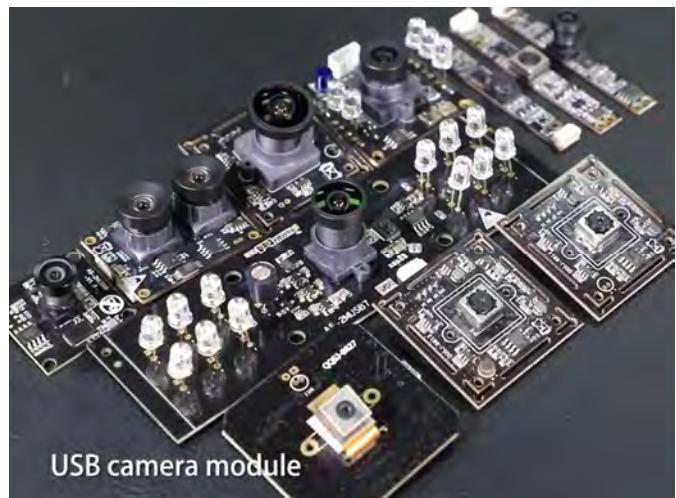


**Company Kai Lap Technologies (KLT)**

Kai Lap Technologies Group Limited. (KLT) was established in 2009, a next-generation technology driven manufacturer specialized in research, design, and produce of audio and video products. KLT is occupying 20,000 square feet automated plants with 100 employees of annual throughput 30,000,000 units cameras.

KLT provides OEM, ODM design, contract manufacturing, and builds the camera products. You may provide the requirements to us, even with a hand draft, our sales and engineering work together to meet your needs. We consider ourselves your last-term partner in developing practical and innovative solutions.

Our team covers everything from initial concept development to mass produced product. KLT specializes in customized camera design, raw material, electronic engineering, firmware/software development, product testing, and packing design. Our experienced strategic supply systems offer a robust and dependable manufacturing capacity for orders of various sizes.

**Limited Warranty**

KLT provides the following limited warranty if you purchased the Product(s) directly from KLT company or from KLT's website, [www.KaiLapTech.com](http://www.KaiLapTech.com). Product(s) purchased from other sellers or sources are not covered by this Limited Warranty. KLT guarantees that the Product(s) will be free from defects in materials and workmanship under normal use for a period of one (1) year from the date you receive the product ("Warranty Period").

For all Product(s) that contain or develop material defects in materials or workmanship during the Warranty Period, KLT will, at its sole option, either: (i) repair the Product(s); (ii) replace the Product(s) with a new or refurbished Product(s) (replacement Product(s) being of identical model or functional equivalent); or (iii) provide you a refund of the price you paid for the Product(s).

This Limited Warranty of KLT is solely limited to repair and/or replacement on the terms set forth above. KLT is not reliable or responsible for any subsequent events.



## KLT Strength

## Powerful Factory



## Professional Service



## Promised Delivery

